TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOS V)

2 S K 2 5 9 8

HIGH SPEED, HIGH VOLTAGE SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS**

: $R_{DS(ON)} = 0.18 \Omega$ (Typ.) Low Drain-Sorce ON Resistance

High Forward Transfer Admittance : $|Y_{fS}| = 13 S$ (Typ.)

Low Leakage Current : $I_{DSS} = 100 \,\mu\text{A}$ (Max.) ($V_{DS} = 250 \,\text{V}$)

: $V_{th} = 1.5 \sim 3.5 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$ Enhancement-Mode

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIS	SYMBOL	RATING	UNIT		
Drain-Source Voltage	${ m v}_{ m DSS}$	250	V		
Drain-Gate Voltage (R _{GS} = $20 \text{ k}\Omega$)		${ m v_{DGR}}$	250	V	
Gate-Source Voltage	v_{GSS}	±20	V		
Drain Current	DC	$I_{\mathbf{D}}$	13	A	
	Pulse	I_{DP}	52		
Drain Power Dissipation	$P_{\mathbf{D}}$	60	W		
Single Pulse Avalanche Energy**		EAS	148	mJ	
Avalanche Current	I_{AR}	13	A		
Repetitive Avalanche En	E_{AR}	6	mJ		
Channel Temperature	$\mathrm{T_{ch}}$	150	°C		
Storage Temperature Range		$\mathrm{T_{stg}}$	-55~150	°C	

THERMAL CHARACTERISTICS

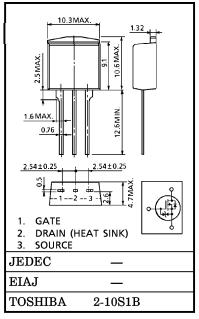
CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	R _{th (ch-c)}	2.08	°C/W
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}	83.3	°C/W

Note;

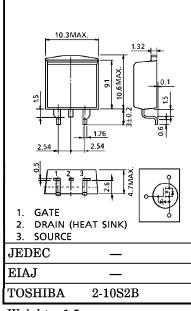
- Repetitive rating; Pulse Width Limited by Max. junction temperature.
- ** V_{DD} = 50 V, Starting T_{ch} = 25°C, L = 1.48 mH, R_{G} = 25 Ω , I_{AR} = 13 A

This transistor is an electrostatic sensitive device. Please handle with caution.

INDUSTRIAL APPLICATIONS TO-220FL Unit in mm



TO-220SM Unit in mm



Weight: 1.5 g

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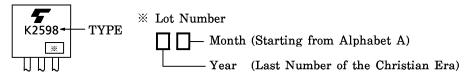
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	e Current	I_{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μ A
Drain Cut-of	f Current	$I_{ m DSS}$	$V_{DS} = 250 \text{ V}, \ V_{GS} = 0 \text{ V}$	1	_	100	μ A
Drain-Source Voltage	Breakdown	V (BR) DSS	$I_{ m D} = 10 { m mA}, \; { m V}_{ m GS} = 0 { m V}$	250	_	_	V
Gate Thresho	old Voltage	$ m v_{th}$	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	1.5	_	3.5	V
Drain-Source	ON Resistance	R _{DS} (ON)	$V_{GS} = 10 \text{ V}, I_{D} = 6.5 \text{ A}$		0.18	0.25	Ω
Forward Trai	nsfer Admittance	$ Y_{fs} $	$V_{DS} = 10 \text{ V}, I_{D} = 6.5 \text{ A}$	6	13	<u> </u>	S
Input Capaci	tance	C_{iss}	V 10 V V 0 V	_	1800	_	
		$\mathrm{C}_{\mathrm{rss}}$	VDS = 10 V, VGS = 0 V,		130	_	рF
			1	500	_		
Switching Time Fal	Rise Time	t_r	$V_{GS} = 0 \text{ V}$ $V_{GS} = 0 \text{ V}$ $V_{DD} = 130 \text{ V}$ $V_{IN} : t_r, t_f < 5 \text{ ns},$ $Duty \leq 1\%, t_w = 10 \mu\text{s}$	1	15	_	
	Turn-on Time	t _{on}			25	_	n a
	Fall Time	tf		_	10	_	ns
	Turn-off Time	t _{off}		_	70	_	
Total Gate Charge (Gate-Source Plus Gate-Drain)		Q_{g}	$V_{DD} = 200 \text{ V}, V_{GS} = 10 \text{ V},$	_	40	_	nC
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$	$I_{\mathrm{D}} = 13 \mathrm{A}$	_	25	_	nC -
Gate-Drain ("Miller") Charge		\mathbf{Q}_{gd}		_	15	_	

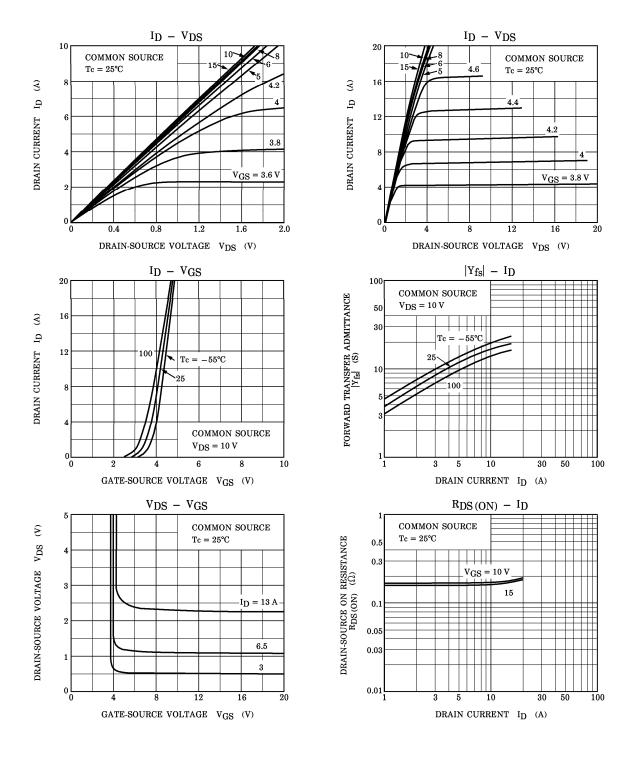
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

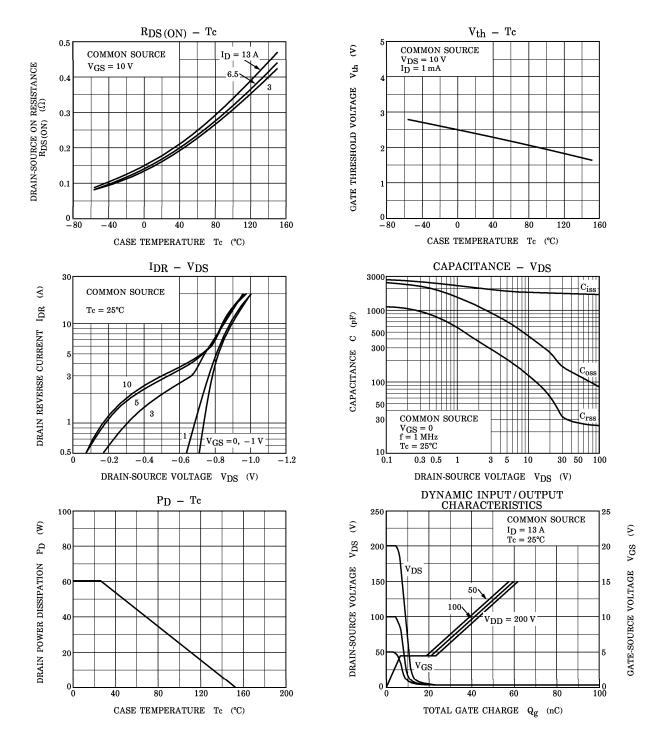
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	13	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_	_	52	A
Diode Forward Voltage	$v_{ m DSF}$	$I_{DR} = 13 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-2.0	V
Reverse Recovery Time	${ m t_{rr}}$	$I_{DR} = 13 \text{ A}, V_{GS} = 0 \text{ V}$	_	260	_	ns
Reverse Recovery Charge	$Q_{ m rr}$	$\mathrm{dI}_{\mathrm{DR}}/\mathrm{dt} = 100\mathrm{A}/\mu\mathrm{s}$	_	0.3	_	μ C

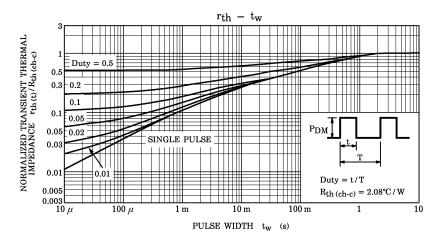
MARKING

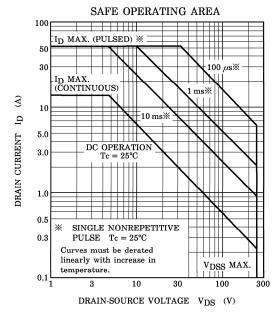


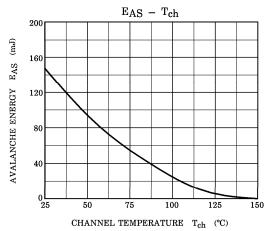
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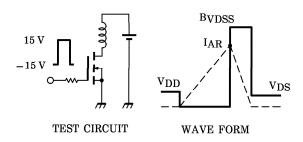












$$\begin{array}{ll} Peak~I_{AR}=13~A,~R_{G}=25~\Omega \\ V_{DD}=50~V,~L=1.48~mH \end{array} \quad E_{AS}=\frac{1}{2}\cdot L\cdot I^{2}\cdot \left(\frac{BVDSS}{BVDSS-V_{DD}}\right)$$